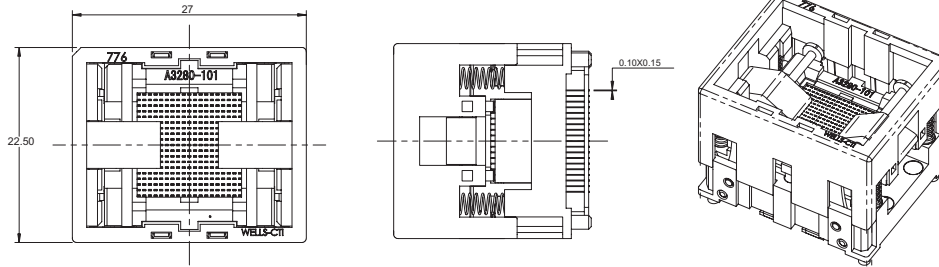


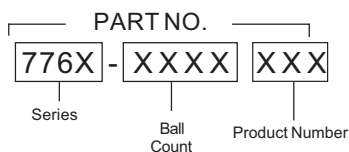
776 Series Open Top CSP Socket

- Low cost / high performance achieved through use of carrier loaded stamped contact
- "U" contact supports any type of solder ball shape and composition
- Compact outline and low actuation force achieved through use of advanced latching mechanism
- Economical customization and pin pitch expansion enabled by maximized component standardization



Pitch e (mm)	Pin Count	Package Size	Pin Matrix.	Ball Dia. (mm)	Ball Height (mm)	Ball Composition	Socket P/N
0.50	40	8X9.2	10X4	0.30	0.25	Eutectic	776B4040-101
	48	6X4	11X6	0.32	0.20	Pb-free	776B4048-101
	56	6X6	10X10	0.30	0.25	Pb-free	776B4056-101
	64	5X5	8X8	0.30	0.22	Pb-free	776B4064-101
	84	6X6	10X10	0.30	0.15 min.	Pb-free	776B4084-101
	88	7X7	13X13	0.29	0.04	Pb-free	776B4088-101
	189	12X13	22X24	0.30	0.20	Pb-free	776B4189-101
	368	13X13	24X24	0.30	0.22	Pb-free	776B4368-101
0.65	100	8X8	10X10	0.35	0.25	Eutectic	776A3100-101
	121	8X8	11X11	0.30	0.20	Pb-free	776A3121-101
	145	10X11	15X15	0.35	0.17	Eutectic	776A3145-101
	154	8X10	11X14	0.30	0.20	Pb-free	776A3154-101
	168	10X10	12X14	0.30	0.21	Pb-free	776A3168-101
	168	12X12	12X14	0.30	0.21	Pb-free	776A3168-102
	232	13X13	18X18	0.40	0.33	Eutectic	776A3232-101
	234	13X13	19X19	0.30	0.20	Pb-free	776A3234-101
	237	13X13	19X19	0.40	0.15 min.	Pb-free	776A3237-101
	260	13X13	18X18	0.40	0.33	Pb-free	776A3260-101
	280	13X13	19X19	0.30	0.20	Eutectic	776A3280-101
	289	14X14	19X19	0.33	0.23	Eutectic	776A3289-101

DESCRIPTION & ORDERING INFORMATION

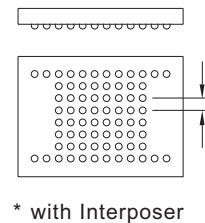
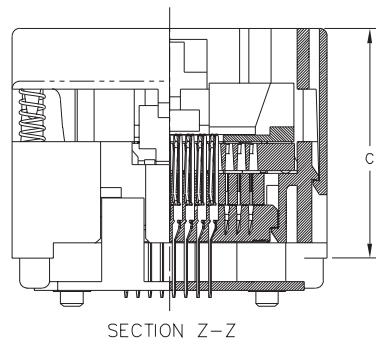
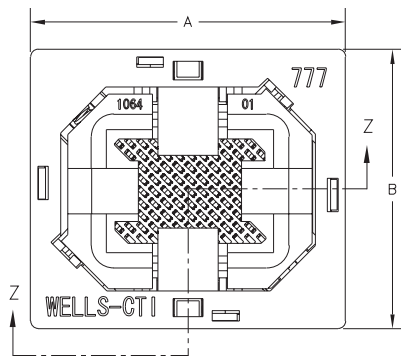


MATERIALS & SPECIFICATIONS

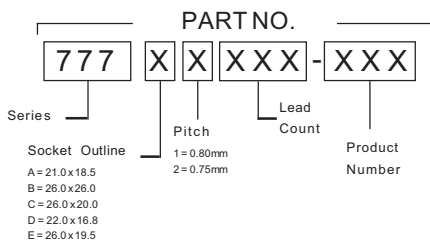
- Socket Body: PES, PEI, LCP or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: Gold
- Contact Force: 10 grams for Eutectic Solder Ball
17 grams for lead-free Solder Ball
- Contact Resistance: 200 mΩ
- Temperature Rating: 150°C
- Durability: 10,000 cycles min.

777 Series OTCSP Pinch Socket

- Open Top Chip Scale Package
- Accommodates pitch sizes of 0.75mm and 0.80mm
- Compact size and Low Actuation Force
- 4-Point pinch design for enhanced electrical contact
- Unique mechanism to eliminate solder ball sticking
- Field replaceable package location plate



DESCRIPTION & ORDERING INFORMATION



MATERIALS & SPECIFICATIONS

- Socket Body: PES, PEI, LCP or Equivalent
- Contacts: Beryllium Copper Alloy
- Contact Plating: NiPd or Gold
- Contact Normal Force: 10 grams
- Contact Resistance: 100 mΩ max.
- Dielectric: 700V AC for 1 minute
- Insulation Resistance: 1,000 MΩ@ 500V DC
- Temperature Rating: 150°C
- Durability: 10,000 cycles min.

777 Series - 0.75mm Pitch OTCSP Pinch Socket



Pitch e (mm)	Ball Count	Package Size	Contact Matrix.	Ball Dia. (mm)	Ball Height (mm)	Contact Plating	Socket P/N	Socket Outline(mm)
0.75	28	6X8	6X8	0.37	0.23	Au	777D2028-201	16.8X22
	29	6X8	6X9	0.37	0.23	Au	777D2029-201	16.8X22
	36	7.01X8.54	6X8	0.476	0.42	Au	777D2036-202	16.8X22
	44	7X7	7X7	0.33	0.20min.	Au	777D2044-201	16.8X22
	46	6.5X7	6X8	0.33	0.40max.	NiPd	777D2046-101	16.8X22
	48	6.5X6.5	6X8	0.35	0.25	NiPd	777C2048-101	20X26
	48	6.5X9.8	6X8	0.35	0.25	NiPd	777C2048-102	20X26
	48	6X9	6X8	0.35	0.25	NiPd	777D2048-103	16.8X22
	48	6X8	6X8	0.40	0.26	NiPd	777D2048-104	16.8X22
	48	6X8	6X8	0.37	0.23	Au	777D2048-204	16.8X22
	48	7X8	6X8	0.40	0.26	NiPd	777D2048-105	16.8X22
	48	8X10	6X8	0.40	0.30	NiPd	777D2048-106	16.8X22
	48	9X7.7	6X8	0.375	0.27	NiPd	777D2048-107	16.8X22
	48	9X11	6X8	0.36	0.27	NiPd	777D2048-108	16.8X22
	48	6.5X10	6X8	0.40	0.35	NiPd	777D2048-109	16.8X22
	48	6X7	6X8	0.40	0.32	NiPd	777D2048-110	16.8X22
	54	6X8	6x9	0.37	0.23	NiPd	777D2054-101	16.8X22
	54	6X8	6X9	0.37	0.23	Au	777D2054-201	16.8X22
	56	7.7X9.3	8X7	0.35	0.25	Au	777D2056-101	16.8X22
	56	9X11	7X8	0.35	0.25	Au	777D2056-102	16.8X22
56	8.5X10	8X7	0.35	0.27	NiPd	777D2056-103	16.8X22	
56	7.7X9	8X7	0.375	0.23	Au	777D2056H105C	16.8X22	



777 Series - 0.80mm Pitch OTCSP Pinch Socket

Pitch e (mm)	Ball Count	Package Size	Contact Matrix.	Ball Dia. (mm)	Ball Height (mm)	Contact Plating	Socket P/N	Socket Outline(mm)
0.80	25	5X5	5X5	0.50	0.25min.	NiPd	777A1025-101	18.5X21
	30	5X5	6X6	0.40	0.20min.	NiPd	777A1030-101	18.5X21
	48	6X11	6X8	0.40	0.35	NiPd	777A1048-101	18.5X21
	48	6X8	6X8	0.40	0.30	NiPd	777A1048-102	18.5X21
	48	6X9	6X8	0.45	0.32	NiPd	777A1048-103	18.5X21
	48	6.15X8.15	6X8	0.38	0.23	Au	777A1048H111C	18.5X21
	48	10.95X11.95	6X8	0.45	0.40	Au	777B1048-101	26X26
	48	11X12	6X8	0.30	0.20min.	NiPd	777B1048-102	26X26
	48	10.95X11.95	6X8	0.35	0.30	Au	777B1048-103	26X26
	48	11X12	6X8	0.30	0.20min.	Au	777B1048-104	26X26
	48	8.5X15	6X8	0.35	0.27	Au	777E1048-202	19.5X26
	48	8.5X15	6X8	0.35	0.27	Au	777E1048H202	19.5X26
	48	8X10	6X8	0.45	0.25min.	Au	777E1048H203	19.5X26
	48	9.5X12	6X8	0.45	0.25min.	Au	777E1048H204	19.5X26
	48	9X11	6X8	0.45	0.25min.	Au	777E1048H204	19.5X26
	54	8X8	9X9	0.45	0.35	Au	777E1054-101	19.5X26
	56	7X9	8X8	0.40	0.22	Au	777A1056H102C	18.5X21
	56	8X11.6	8X8	0.35	0.30	Au	777E1056H101C	19.5X26
	56	8X13	8X8	0.35	0.30	Au	777E1056-102	19.5X26
	56	8X10	8X8	0.38	0.25	Au	777E1056-103	19.5X26
	56	8X11.6	8X8	0.38	0.25	Au	777E1056-105	19.5X26
	59	8X11.6	8X8	0.38	0.25	Au	777E1059-101	19.5X26
	60	8X16/11x13	8X15	0.45	0.35	NiPd	777E1060-101	19.5X26
	60	8X11.6	8X8	0.35	0.30	Au	777E1060-103	19.5X26
	60	9X12	8X10	0.40	0.15	Au	777E1060-106	19.5X26
	60	8X11.6	8X10	0.38/0.40	0.22/0.23/0.25	Au	777E1060H107C	19.5X26
	63	7X11	8X12	0.40	0.30	NiPd	777A1063-101	18.5X21
	64	8X11	8X8	0.45	0.35	NiPd	777A1064-101	18.5X21
	64	8.1X11.1	8X8	0.45	0.35	NiPd	777A1064-102	18.5X21
	64	7X7	8X8	0.40	0.32	Au	777A1064-203	18.5X21
	64	7.95X8.95	8X8	0.35	0.25	Au	777A1064-105	18.5X21
	64	7X7	8X8	0.50	0.25min.	NiPd	777A1064-106	18.5X21
	64	7X7	8X8	0.50	0.25min.	Au	777A1064-206	18.5X21
	64	9X9	8X8	0.45	0.39	NiPd	777B1064-101	26X26
	64	10.95X11.95	8X8	0.30	0.20min.	Au	777B1064-102	26X26
	64	9X11.5	8X8	0.35	0.25	Au	777B1064-103	26X26
	64	9X13	10X10	0.35	0.30	Au	777E1064-104	19.5X26
	64	7.95X8.95	8X8	0.38	0.23	Au	777E1064-106	19.5X26
	66	7.47X11.02	7X10	0.46	0.42	Au	777A1066-201	18.5X21
	80	8X8	9X9	0.40	0.21min.	NiPd	777A1080-101	18.5X21
	80	8X11	8X10	0.38	0.25	Au	777A1080-104	18.5X21
	80	8X11	8X11	0.38	0.23	Au	777A1080H105C	18.5X21
	80	7X9	8X10	0.40	0.22	Au	777A1080H106C	18.5X21
	80	8X14	8X14	0.40	0.30min.	NiPd	777B1080-101	26X26
	80	9.65X11.95	8x10	0.35	0.25	Au	777B1080-102	26x26
	80	9X11.5	8X10	0.35	0.20min.	Au	777B1080-103	26X26
	80	9.65X11.95	8X10	0.38	0.23	Au	777B1080H105	26X26
	80	8X11.6	8X10	0.35	0.30	Au	777E1080-101	19.5X26
	80	10X10	8X10	0.35	0.25/0.30	Au	777E1080-103	19.5X26
	80	8x11.6	10x12	0.35	0.30	Au	777E1080-104	19.5X26
80	10.5X10.5	8X10	0.34	0.23	Au	777E1080-105	19.5X26	
80	9X13	8X10	0.34	0.23	Au	777E1080-106	19.5X26	
80	10X13	8X10	0.35	0.30	Au	777E1080-107	19.5X26	
80	8X10	8X10	0.38	0.25	Au	777E1080-108	19.5X26	
80	8X11.6	8X10	0.40	0.22/0.23	Au	777E1080H112C	19.5X26	
80	9.65X11.95	8X10	0.38	0.23	Au	777E1080H115C	19.5X26	

Continued on next page



777 Series - 0.80mm Pitch OTCSP Pinch Socket

Pitch e (mm)	Ball Count	Package Size	Contact Matrix.	Ball Dia. (mm)	Ball Height (mm)	Contact Plating	Socket P/N	Socket Outline(mm)
0.80	80	9X12	8X10	0.40	0.22	Au	777E1080-113	19.5X26
	81	8X8	9X9	0.40	0.35	NiPd	777A1081-101	18.5X21
	81	10.4X10.8	12X12	0.45	0.33	NiPd	777B1081-101	26X26
	81	9X9	9X9	0.33	0.23	Au	777E1081-101	19.5X26
	84	9.5X14.5	9X10	0.45	0.36	Au	777E1084-101	19.5X26
	84	8X11	9X10	0.45	0.36	Au	777E1084-102	19.5X26
	84	8X11.6	10X12	0.38	0.23	Au	777E1084H103C	19.5X26
	88	8X11	8X12	0.35	0.25	Au	777E1088-101	19.5X26
	88	9.6X12	8X12	0.375	0.20min.	Au	777E1088-202	19.5X26
	88	8X11	8X12	0.375	0.25	Au	777E1088H103C	19.5X26
	89	8X11.6	10X10	0.38	0.25	Au	777E1089-101	19.5X26
	89	8X11.6	10X10	0.35-0.40	0.17min.	Au	777E1089H102U	19.5X26
	90	11X13	9X15	0.40	0.32	NiPd	777E1090-102	19.5X26
	90	8.5X15	9X15	0.42	0.30	Au	777E1090-201	19.5X26
	90	9X13	9X15	0.45	0.33	NiPd	777E1090HX03	19.5X26
	90	8X13	9X15	0.45	0.325	Au	777E1090-204	19.5X26
	92	10.5X18	10X18	0.45	0.35	Au	777E1092-101	19.5X26
	92	9.3X15.1	10X18	0.45	0.35	Au	777E1092-102	19.5X26
	93	11X14	12X17	0.46	0.37	Au	777F1093-201	22X26
	100	10X10	10X10	0.40	0.20min.	NiPd	777B1100-101	26X26
	100	9X9	10X10	0.43	0.33	NiPd	777B1100-102	26X26
	100	9X14	10X10	0.45	0.35	Au	777E1100-101	19.5X26
	100	9X13	10X10	0.34	0.25	Au	777E1100-103	19.5X26
	100	9X14	10X10	0.45	0.35	Au	777E1100-104	19.5X26
	100	9X12	10X10	0.34	0.25	Au	777E1100-105	19.5X26
	103	14X14	9X12	0.35/0.375	0.19/0.27	Au	777B1103-201	26X26
	106	12X12	14X14	0.40	0.30	Au	777B1106H201	26X26
	107	11X13	10X14	0.47	0.35	Au	777E1107H202C	19.5X26
	108	14X14	9X12	0.35/0.375	0.19/0.27	Au	777B1108-201	26X26
	108	9X11	9X12	0.38	0.25	Au	777E1108-101	19.5X26
	108	9X11	9X12	0.35	0.20min.	Au	777E1108H202	19.5X26
	115	11.3X10.8	13X13	0.46	0.42	Au	777B1115-201	26X26
	115	9X14	10X14	0.45	0.35	Au	777E1115-101	19.5X26
	115	9X12	10X14	0.40	0.15	Au	777E1115H102C	19.5X26
	119	15.09X11.13	15X11	0.46	0.42	Au	777B1119-201	26X26
	120	9X14	10X12	0.45	0.35	Au	777E1120-102	19.5X26
	128	11X11	12X12	0.45	0.35	NiPd	777B1128-101	26X26
	136	11X14	12X17	0.46	0.37	Au	777F1136-201	22X26
	139	8X11.6	10X14	0.35	0.20min.	Au	777E1139-201	19.5X26
	140	9X12	10X14	0.40	0.22	Au	777E1140H101C	19.5X26
	144	11X11	12X12	0.45	0.35	NiPd	777B1144-101	26X26
	144	10X10	12X12	0.40	0.20min.	NiPd	777B1144-102	26X26
144	12X12	12X12	0.45	0.35	NiPd	777B1144-103	26X26	
144	12X12	12X12	0.45	0.35	NiPd	777B1144H103	26X26	
150	10.6X16.1	10X17	0.40	0.30	Au	777E1150-201	19.5X26	
151	9X13	10X14	0.40	0.22	Au	777E1151-101	19.5X26	
175	13X13	15X15	0.45	0.35	NiPd	777B1175-101	26X26	
176	13X13	15X15	0.46	0.36	NiPd	777B1176-101	26X26	
196	12X12	14X14	0.50	0.27min.	Au	777B1196-201	26X26	
225	13X13	15X15	0.40	0.20min.	NiPd	777B1225-102	26X26	
225	13X13	15X15	0.40	0.20min.	Au	777B1225-202	26X26	
225	13X13	15X15	0.40	0.20min.	Ni-B	777B1225-302	26X26	
0.8X1.0	55	11X18.5	12X18	0.35	0.24	Au	778A1055-101	19.5X26
	55	11X18.5	12X18	0.51	0.39	Au	778A1055-102	19.5X26
	144	11X18.5	12X18	0.35	0.24	Au	778A1144-101	19.5X26
	144	11X18.5	12X18	0.51	0.39	Au	778A1144-102	19.5X26

717M and 718M Series Multisite Clamshell CSP/LGA Socket for 0.50mm and 1.00 mm pitch CSP Packages

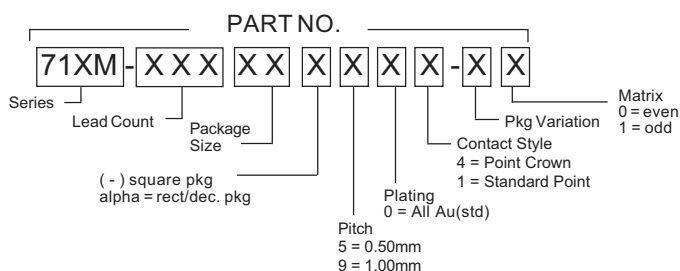


- Apply up to 4 devices per socket
- Individual pressure pad per device
- Multi-device applications for devices smaller than 6mm x 6mm
- Lower cost per device than single site sockets
- Lower socket investment for your small CSP application
- Maximize throughput and yield

Pitch e (mm)	Lead Count	Package Size (mm)	Matrix	Devices per Socket	Part Number
1.00	5	4.11 x 3.45	3 x 3	4	718M00504B904-A1
	8	3.00 x 3.00	6 x 6	4	718M00803-904-A1
	8	6.10 x 4.32	5 x 3	2	718M00806C904-A1
	12	9.27 x 3.68	7 x 3	2	718M01209E904-A1
	19	6.35 x 4.60	6 x 4	4	718M01906B904-A1
	20	6.43 x 4.57	6 x 4	2	718M02006D904-A1
	20	5.03 x 4.47	5 x 4	4	718M02005D904-A1

Contact your local Sales Representative for implementing your device, or call 800.348.2505.

DESCRIPTION & ORDERING INFORMATION

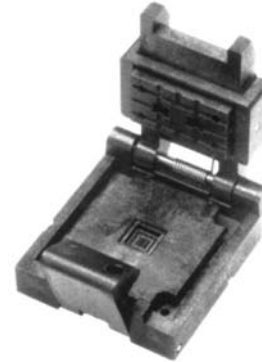
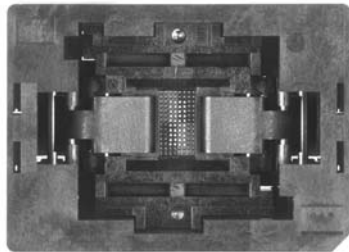


MATERIALS & SPECIFICATIONS

- Socket Body: PEI, PES, or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: Gold over Nickel
- Contact Normal Force: 12-15 grams typical
- Contact Resistance: 350 mΩ typical
- Temperature Rating: Burn-in @ 125°C
- Durability: 10,000 cycles min.

71XP Series Open Top and Clamshell CSP/LGA Socket for 0.50mm pitch CSP Packages with High Performance Pogo Pin

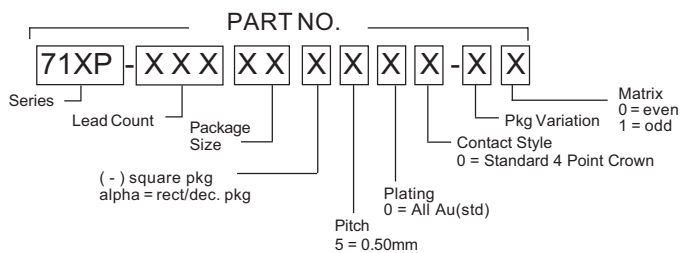
- High performance spring probe contacts
- Low cost/high performance solution for lab and evaluation applications
- Low inductance contact
- Compression surface mount
- Open top or clamshell options



Current Rating: 0.5A Continuous
 Self Inductance: 0.87nH
 Mutual Inductance: 0.69nH
 Bandwidth (*Dielectric material: ULTEM1000*): -1dB @ 6.00GHz
 -3dB @ 21.00GHz

Contact your local Sales Representative for implementing your device, or call 800.348.2505.

DESCRIPTION & ORDERING INFORMATION

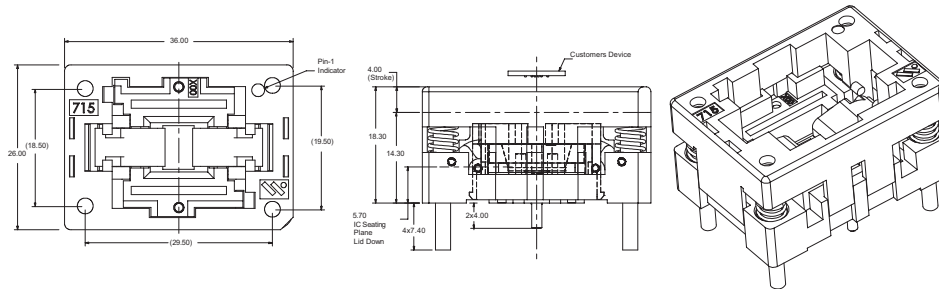
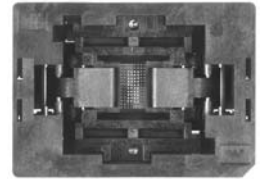


MATERIALS & SPECIFICATIONS

- Socket Body: PEI, PES, or Equivalent
- Contact: Plunger - Hardened BeCu/Au plated
Barrel - Phosphor Bronze/Au plated
Spring - Stainless Steel/Au plated
- Contact Plating: Gold over Nickel
- Contact Normal Force: 12-15 grams typical
- Contact Resistance: Less than 50 mΩ
- Temperature Rating: -55°C to 150°C
- Durability: 10,000 cycles min.

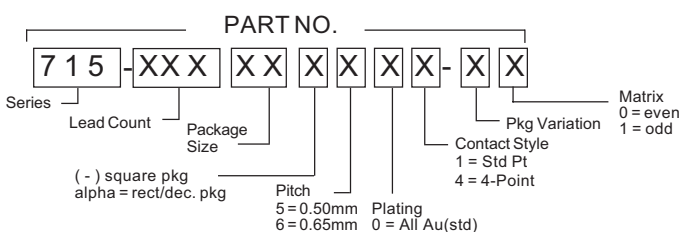
715 Series Open Top CSP Socket for Microarray Packages

- Open Top Chip Scale Package
- Compression surface mount
- Spring and probe contact
- Pointed probe maintains continuous contact to PCB
- Spring loaded floating locator plate



Pitch e (mm)	Lead Count	Package Size (mm)	Matrix	Ball Dia. (mm)	Part Number
0.50	40	8 X 11.5	4 X 10	0.25-0.35	715-04011A50X-XX
	40	9 X 7.7	8 X 14	0.25-0.35	715-04009A50X-XX
	40	9 X 7.7	10 X 4	0.259-0.359	715-04009A504-A2
	40	9.2 X 8.0	12 X 18	0.25-0.35	715-04009B50X-XX
	40	9.95 X 6.95	8 X 14	0.25-0.35	715-04099C50X-XX
	40	11 X 10	10 X 4	0.25-0.35	715-04011B504-A0
	44	9 X 7.7	8 X 14	0.25-0.35	715-04409A50X-XX
	48	10.53 X 6.29	8 X 14	0.25-0.35	715-04810A50X-XX
	52	8 X 6	13 X 4	0.25-0.35	715-05208A504-A1
	54	8.2 X 6.0	9 X 10	0.25-0.35	715-05408A50X-XX
	56	6 X 6	10 X 10	0.27-0.37	715-05606-504-A0
	56	9 X 9	10 X 10	0.25-0.35	715-05609-50X-XX
	64	5 X 5	8 X 8	0.25-0.35	715-06405-504-A0
	64	6 X 6	10 X 10	0.25-0.35	715-06406-50X-XX
	80	5 X 5	10 X 10	0.25-0.35	715-08005-50X-XX
	80	7 X 7	12 X 12	0.25-0.35	715-08007-504-A0
	84	6 X 6	10 X 10	0.25-0.35	715-08406-50X-XX
	84	7 X 7	12 X 12	0.25-0.35	715-08407-50X-XX
	88	6 X 6	11 X 11	0.25-0.35	715-08806-504-A1
	96	6 X 6	11 X 11	0.25-0.35	715-09606-504-A1
	96	8 X 8	14 X 14	0.25-0.35	715-09608-504-A0
	100	6 X 6	10 X 10	0.25-0.35	715-10006-504-A0
	108	7 X 7	12 X 12	0.25-0.35	715-10807-50X-XX
	108	8 X 8	14 X 14	0.25-0.35	715-10808-50X-XX
	112	7 X 7	12 X 12	0.27-0.37	715-11207-504-A0
	132	8 X 8	14 X 14	0.27-0.37	715-13208-504-A0
	137	9 X 9	15 X 15	0.25-0.35	715-13709-504-A1
	144	7.8 X 7.8	13 X 13	0.25-0.35	715-14407-50X-XX
	144	8 X 8	14 X 15	0.25-0.35	715-14408-50X-XX
	148	9 X 9	16 X 16	0.25-0.35	715-14809-504-A0
	160	7.8 X 7.8	14 X 14	0.25-0.35	715-16007-50X-XX
	160	8 X 8	14 X 14	0.25-0.35	715-16008-504-A0
	164	7.75 X 7.85	13 X 13	0.25-0.35	715-16407-504-A0
169	9 X 9	16 X 16	0.25-0.35	715-16909-504-A0	
180	10 X 10	18 X 18	0.29-0.39	715-18010-504-A0	
180	10 X 10	18 X 18	0.25-0.35	715-18010-504-A0	
196	8 X 8	14 X 14	0.25-0.35	715-19608-504-A0	
0.65	71	7 X 7	9 X 9	0.28-0.38	715-07107-604-A1
	96	8 X 8	11 X 11	0.25-0.35	715-09608-604-A1

DESCRIPTION & ORDERING INFORMATION

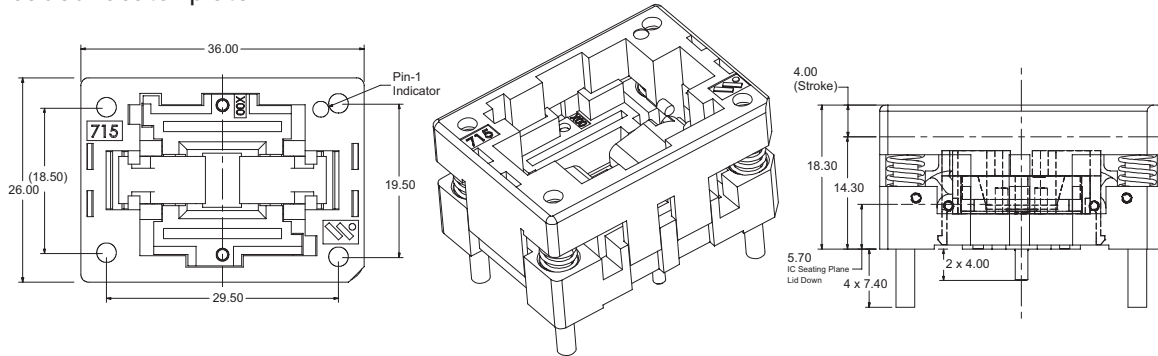
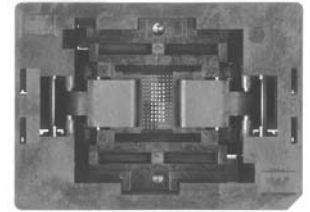


MATERIALS & SPECIFICATIONS

- Socket Body: PEI, PES, or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: Gold over Nickel
- Contact Normal Force: 12-15 grams typical
- Contact Resistance: 350 mΩ typical
- Temperature Rating: Burn-in @ 125°C
- Durability: 10,000 cycles min.

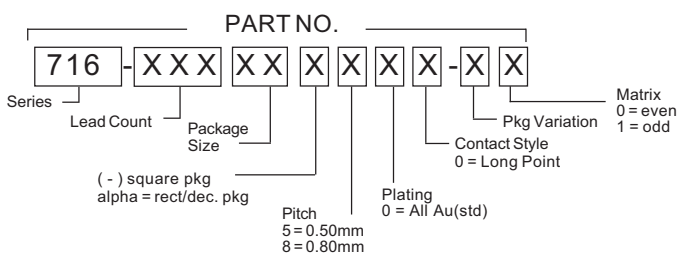
716 Series Open Top LGA Socket for Microarray Packages

- Open Top Land Grid Array
- Compression surface mount
- Spring and probe contact
- Pointed probe contacts solder pad
- Pointed probe maintains continuous contact to PCB
- Spring loaded locator plate



Pitch e (mm)	Lead Count	Package Size (mm)	Matrix	Ball Dia. (mm)	Part Number
0.50	40	9 X 7.7	4 X 10	0.25 min	716-04009A50X-XX
	40	8 X 11.5	4 X 10	0.25 min	716-04011A50X-XX
	44	9 X 7.7	4 X 10	0.25 min	716-04409A50X-XX
	48	10.53 X 6.29	4 X 10	0.25 min	716-04810A50X-XX
	56	6 X 6	10 X 10	0.25-0.35	716-05606B500-A0
	56	9 X 9	10 X 10	0.25 min	716-05609-50X-XX
	64	6 X 6	10 X 10	0.25 min	716-06406-50X-XX
	72	10 X 14	8 X 12	0.25 min	716-07214A50X-XX
	72	8 X 14	8 X 12	0.25 min	716-07214B50X-XX
	80	5 X 5	10 X 10	0.25 min	716-08005-50X-XX
	84	6 X 6	10 X 10	0.25 min	716-08406-50X-XX
	84	7 X 7	10 X 10	0.25 min	716-08407-50X-XX
	108	8 X 8	14 X 14	0.25 min	716-10808-50X-XX
	120	8 X 8	14 X 14	0.27-0.37	716-12008-500-A0
	144	7.8 X 7.8	13 X 13	0.25 min	716-14407-50X-XX
	144	8 X 8	14 X 15	0.25 min	716-14408-50X-XX
148	9 X 9	16 X 16	0.20-0.30	716-14809-500-A0	
160	7.8 X 7.8	14 X 14	0.25 min	716-16007-50X-XX	
0.80	45	10.9 X 6.4	11 X 5	0.42-0.48	716-04510A800-A1

DESCRIPTION & ORDERING INFORMATION

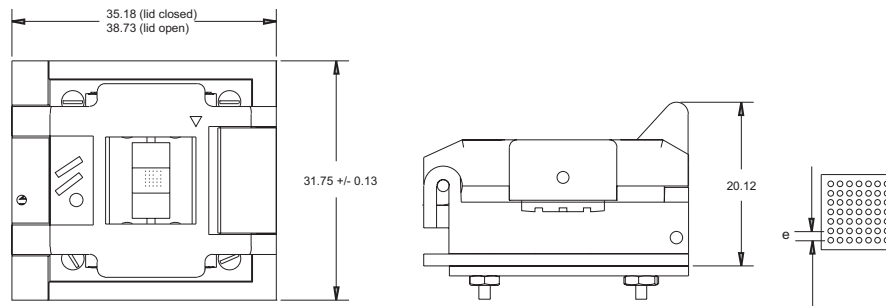


MATERIALS & SPECIFICATIONS

- Socket Body: PEI, PES, or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: Gold over Nickel
- Contact Normal Force: 12-15 grams typical
- Contact Resistance: 350 mΩ typical
- Temperature Rating: Burn-in @ 125°C
- Durability: 10,000 cycles min.

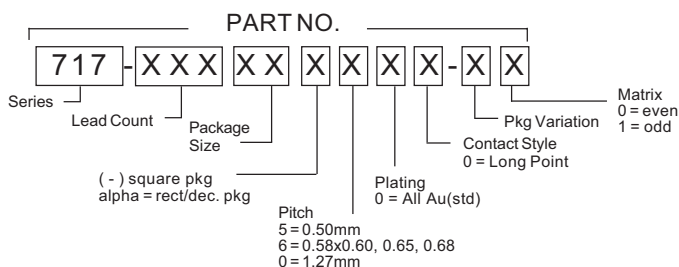
717 Series LGA CSP Socket for Microarray Packages

- Clamshell design, Compression surface mount
- Spring and probe contact
- Pointed probe contacts solder pad
- Pointed probe maintains continuous contact to PCB
- Spring loaded pressure pad and locator plate



Pitch e (mm)	Lead Count	Package Size (mm)	Matrix	Pad Dia. (mm)	Part Number
0.50	15	2.5 X 2.5	4 X 4	0.25-0.35	717-01502A-500-A0
	24	3 X 3	5 X 5	0.25-0.35	717-02403-500-A1
	40	4 X 4	7 X 7	0.25 min.	717-04004-50X-XX
	48	4 X 4	7 X 7	0.25-0.35	717-04804-500-A1
	48	6 X 4	11 X 6	0.24-0.34	717-04806A500-B1
	56	5 X 5	9 X 9	0.25 min.	717-05605-50X-XX
	64	5 X 5	9 X 9	0.20-0.30	717-06405-500-A1
	80	5 X 5	9 X 9	0.25 min.	717-08005-50X-XX
	81	5 X 5	9 X 9	0.25 min.	717-08105-50X-XX
	81	5 X 5	9 X 9	0.25-0.35	717-08105-500-A1
	83	6.22 X 6.22	10 X 10	0.20-0.30	717-08306-500-A0
	96	6 X 6	11 X 11	0.25 min.	717-09606-50X-XX
	112	9 X 9	16 X 16	0.23-0.33	717-11209-500-A0
	120	6 X 6	11 X 11	0.25-0.35	717-12006-500-A1
	120	7 X 7	13 X 13	0.20-0.30	717-12007-500-A1
	143	7 X 7	12 X 12	0.25 min.	717-14307-50X-XX
	144	8 X 8	15 X 15	0.25-0.35	717-14408-500-C1
	148	9 X 9	16 X 16	0.23-0.33	717-14809-500-A0
168	7 X 7	13 X 13	0.25-0.35	717-16807-500-A1	
176	9 X 9	16 X 16	0.23-0.33	717-17609-500-A0	
188	9 X 9	17 X 17	0.25-0.35	717-18809-500-A1	
0.58 X 0.60	22	2.918 X 3.740	4 X 6	0.22-0.28	717-02203A600-A0
0.65	321	15 X 15	21 X 21	0.25-0.35	717-32115-600-A1
0.68	32	5.4 X 3.8	7 X 5	0.22-0.28	717-03205B600-A1
1.27	87	15.5 X 10.5	11 X 8	0.75-0.85	717-08715A000-A1

DESCRIPTION & ORDERING INFORMATION

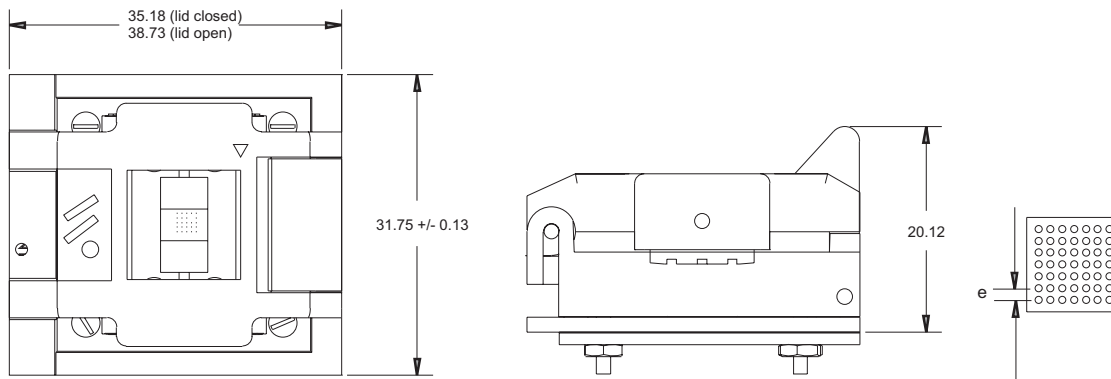
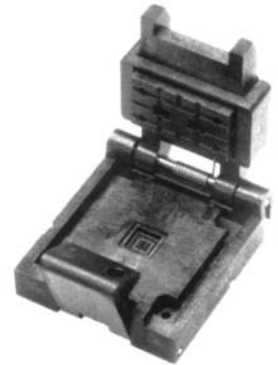


MATERIALS & SPECIFICATIONS

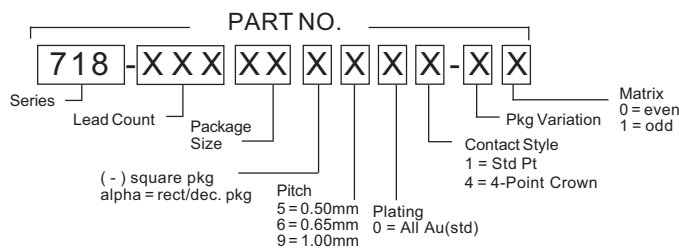
- Socket Body: PEI, PES or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: Gold over Nickel
- Contact Normal Force: 12-15 grams typical
- Contact Resistance: 350 mΩ typical
- Temperature Rating: Burn-in @125°C
- Durability: 10,000 cycles min.

718 Series Clamshell CSP Socket for Microarray Packages

- Clamshell design, Compression surface mount
- Spring and probe contact
- Pointed probe maintains continuous contact to PCB
- Spring loaded pressure pad and locator plate
- 4-Point Crown Solder Balls
- Multi-site options are available



DESCRIPTION & ORDERING INFORMATION



MATERIALS & SPECIFICATIONS

- Socket Body: PEI, PES or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: Gold over Nickel
- Contact Normal Force: 12-15 grams typical
- Contact Resistance: 350 mΩ typical
- Temperature Rating: Burn-in @125°C
- Durability: 10,000 cycles min.

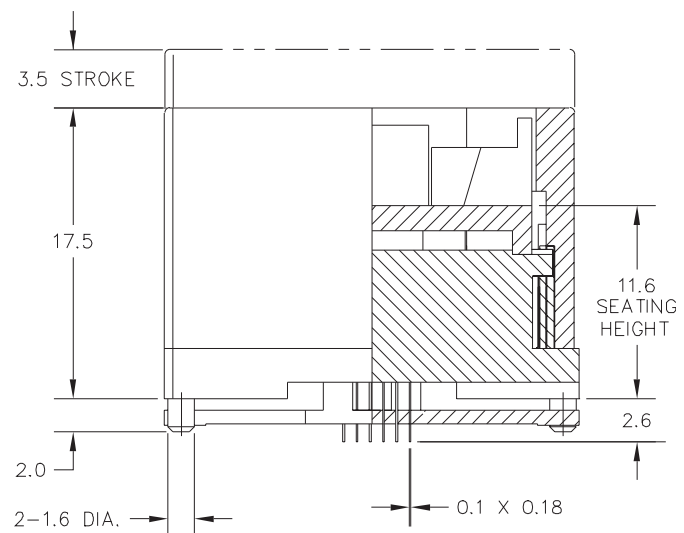
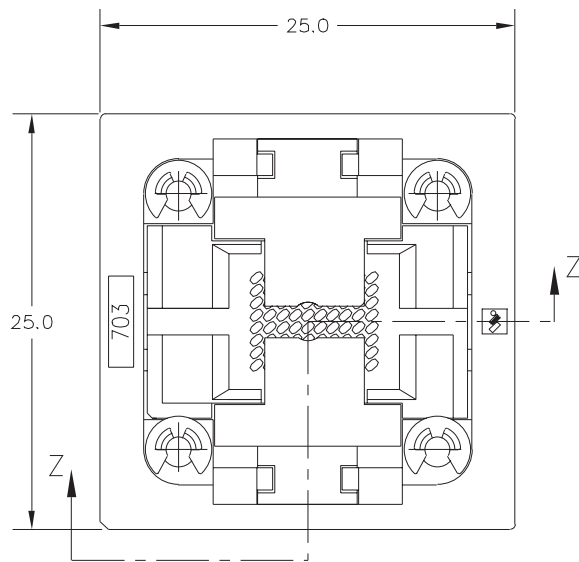
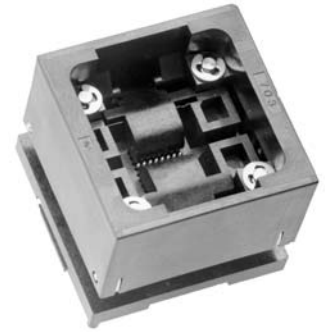


718 Series Clamshell CSP Socket for Microarray Packages

Pitch e (mm)	Lead Count	Package Size (mm)	Matrix	Ball Dia. (mm)	Part Number
0.50	15	2.5 X 2.5	4 X 4	0.25-0.35	718-01502-50X-A0
	16	2 X 2	4 X 4	0.27-0.37	718-01602-50X-A0
	25	2.59 X 2.64	5 X 5	0.27-0.37	718-02502A50X-A1
	40	4 X 4	7 X 7	0.25 min.	718-04004-50X-XX
	40	6.29 X 10.53	4 X 10	0.25 min.	718-04010A50X-XX
	47	4.35 X 4.20	7 X 7	0.25-0.35	718-04704A504-A1
	48	7.06 X 3.25	8 X 6	0.32-0.42	718-04807B504-A0
	56	6 X 6	10 X 10	0.25 min.	718-05606-50X-XX
	56	6 X 6	10 X 10	0.27-0.37	718-05606-504-A0
	56	5 X 5	9 X 9	0.25 min.	718-05605-50X-XX
	57	5 X 5	9 X 9	0.25-0.35	718-05705-504-A1
	64	5 X 5	8 X 8	0.25-0.35	718-06405-504-A0
	64	6 X 6	10 X 10	0.25 min.	718-06406-50X-XX
	72	7 X 7	11 X 11	0.25-0.35	718-07207-504-A1
	80	5 X 5	9 X 9	0.25 min.	718-08005-50X-XX
	80	7 X 7	12 X 12	0.25 min.	718-08007-50X-XX
	81	5 X 5	9 X 9	0.25 min.	718-08105-50X-XX
	84	6 X 6	10 X 10	0.25 min.	718-08406-50X-XX
	84	6.2 X 6.2	10 X 10	0.25 min.	718-08406-50X-XX
	84	7 X 7	12 X 12	0.25 min.	718-08407-50X-XX
	88	6 X 6	11 X 11	0.25-0.35	718-08806-504-A1
	96	6 X 6	11 X 11	0.25 min.	717-09606-50X-XX
	96	6 X 6	11 X 11	0.25-0.35	718-09606-504-A1
	96	8 X 8	14 X 14	0.25 min.	718-09608-50X-XX
	100	6 X 6	10 X 10	0.25 min.	718-10006-50X-XX
	108	7 X 7	12 X 12	0.25 min.	718-10807-50X-XX
	108	8 X 8	14 X 14	0.25 min.	718-10808-50X-XX
	111	6 X 6	11 X 11	0.25-0.35	718-11106-504-A1
	115	7 X 7	12 X 12	0.25 min.	718-11507-50X-XX
	114	8 X 8	14 X 14	0.25 min.	718-14408-50X-XX
	128	8 X 8	13 X 13	0.27-0.37	718-12808-50X-A1
	143	7 X 7	12 X 12	0.25-0.35	718-14307-50X-A0
144	7 X 7	12 X 12	0.25-0.35	718-14407-504-A0	
144	8 X 8	14 X 14	0.27-0.33	718-14408-504-A0	
152	8 X 8	14 X 14	0.25-0.35	718-15208-504-A0	
159	8 X 8	14 X 14	0.26-0.36	718-15908-504-A0	
164	8 X 8	14 X 14	0.25-0.35	718-16408-504-A0	
181	10 X 10	17 X 17	0.27-0.37	718-18110-504-A1	
188	9 X 9	17 X 17	0.25-0.35	718-18809-604-A1	
196	8 X 8	14 X 14	0.28-0.38	718-19608-504-A0	
228	12 X 12	22 X 22	0.25-0.35	718-22812-504-A0	
244	12 X 12	21 X 21	0.25-0.35	718-22412-504-A1	
289	9 X 9	17 X 17	0.28-0.38	718-28909-504-A1	
300	13 X 13	22 X 22	0.25-0.35	718-30013-504-A0	
324	12 X 12	22 X 22	0.25-0.35	718-32412-504-A0	
0.65	49	5 X 5	7 X 7	0.28-0.38	718-04905-604-A1
	121	8 X 8	11 X 11	0.28-0.38	718-12108-604-A1
	280	13 X 13	19 X 19	0.25-0.35	718-28013-604-A1
1.00	16	4 X 4	4 X 4	0.45-0.55	718-01604-904-A1
	26	8.46 X 6.27	6 X 5	0.33-0.43	718-02608A904-A1

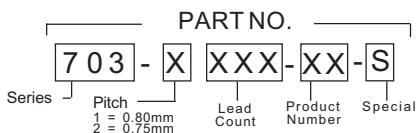
703 Series Open Top CSP Socket

- Zero Insertion Force design for automatic loading
- Patented “Y” contact
- Mechanical ejection plate
- For 0.75mm and 0.80mm pitch packages



SECTION Z-Z
AT FULL STROKE

DESCRIPTION & ORDERING INFORMATION



MATERIALS & SPECIFICATIONS

- Socket Body: PES, PEI, LCP or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: 20 microinches gold over 40 microinches of nickel underplate in contact area; gold flash on solder tail
- Insulation Resistance: 1000 MΩ @ 500V DC
- Dielectric: 700V AC for 1 minute
- Temperature Rating: 150°C
- Contact Resistance: 100 mΩ max.
- Contact Normal Force: 13 grams
- Durability: 10,000 cycles min.

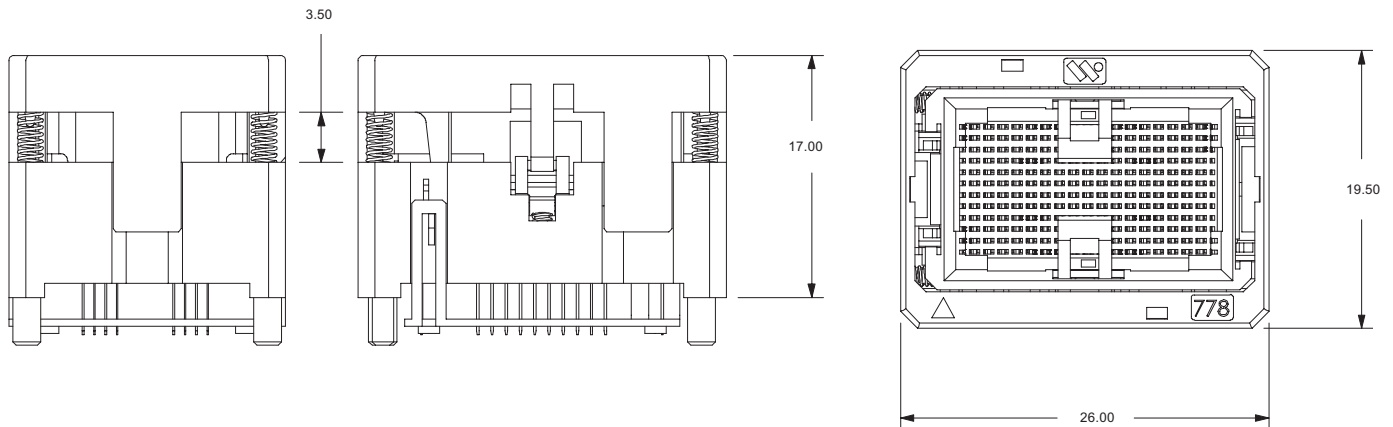


703 Series Open Top CSP Socket

Pitch e (mm)	Lead Count	Package Size (mm)	Contact Matrix	Ball Dimensions (mm)		Part Number
				Diameter	Height	
0.75	40	5.55 x 9.1	4 x 10	0.35	0.25	703-2040-01
	44	7.75 x 14.35	4 x 11	0.35	0.25	703-2044-01
	48	7.1 x 7.18	6 x 8	0.35	0.20 min.	703-2048-01
	48	7.75 x 7.3	6 x 8	0.35	0.25	703-2048-04
	48	9.616 x 6.85	6 x 8	0.35	0.25	703-2048-05
	48	6.62 x 6.8	6 x 8	0.35	0.25	703-2048-06
	48	7.95 x 8.95	6 x 8	0.30	0.25	703-2048-07
	48	10.4 x 7	6 x 8	0.35	0.20 min.	703-2048-08
	48	6.37 x 6.39	6 x 8	0.35	0.20 min.	703-2048-11
	48	10.5 x 6.39	6 x 8	0.35	0.20 min.	703-2048-12
	48	7 x 7	6 x 8	0.45	0.30	703-2048-13
	48	8 x 7	6 x 8	0.45	0.30	703-2048-14
	48	12 x 7	6 x 8	0.45	0.30	703-2048-15
	48	8.1 x 8.1	6 x 8	0.40/0.45	0.23 min.	703-2048-16
	48	12 x 7	6 x 8	0.30	0.20 min.	703-2048-17
	48	8.1 x 8.1	6 x 8	0.40/0.45	0.23 min.	703-2048-18
	48	8 x 10	6 x 8	0.35	0.27	703-2048-19
	48	11.1 x 8.1	6 x 8	0.40/0.45	0.35	703-2048-20
	48	11 x 8	6 x 8	0.40	0.25	703-2048-24
	56	11.1 x 8.1	7 x 8	0.40/0.45	0.22min.	703-2056-01
0.80	40	7.95 x 14.95	4 x 10	0.30	0.25	703-1040-01
	48	6.15 x 8.15	6 x 8	0.40	0.40	703-1048-01
	48	5.95 x 8.95	6 x 8	0.40	0.40	703-1048-02
	48	7.95 x 8.95	6 x 8	0.40	0.40	703-1048-03
	48	7.95 x 13.95	6 x 8	0.45	0.36	703-1048-05
	48	5.95 x 8.95	6 x 8	0.40	0.30	703-1048-06
	48	6.15 x 8.15	6 x 8	0.30	0.25	703-1048-11
	48	10.1 x 8.1	6 x 8	0.45	0.35	703-1048-12
	48	8 x 10	6 x 8	0.45	0.30	703-1048-13-S
	48	7.95 x 8.95	6 x 8	0.30	0.25	703-1048-14
	48	7.95 x 8.95	6 x 8	0.30	0.25	703-1048-14-S
	48	5.95 x 8.95	6 x 8	0.30	0.25	703-1048-15
	48	5.95 x 8.95	6 x 8	0.30	0.25	703-1048-15-S
	48	6 x 12	6 x 8	0.30	0.25	703-1048-16
	48	6 x 12	6 x 8	0.30	0.25	703-1048-16-S
	48	11.1 x 8.1	6 x 8	0.45	0.35	703-1048-17
	48	8.1 x 8.1	6 x 8	0.45	0.392	703-1048-18
	48	6.05 x 9.05	6 x 8	0.45	0.33	703-1048-19
	49	7 x 7	7 x 7	0.46	0.36	703-1049-01
	49	6 x 6	7 x 7	0.48	0.30	703-1049-02
	56	7.92 x 8.28	7 x 8	0.32	0.23	703-1056-01
	56	8 x 10	8 x 8	0.45	0.32	703-1056-03
	60	8.1 x 11.1	8 x 12	0.45	0.35	703-1060-02
	63	8 x 14	8 x 12	0.30	0.25	703-1063-02
	64	8.1 x 11.1	8 x 8	0.45	0.35	703-1064-01
	64	8.1 x 11.1	8 x 8	0.45	0.35	703-1064-01-S
	64	8.1 x 8.1	8 x 8	0.45	0.35	703-1064-02
	64	8.1 x 8.1	8 x 8	0.45	0.35	703-1064-02-S
	64	7.95 x 13.95	8 x 8	0.45	0.36	703-1064-03
	64	7.95 x 13.95	8 x 8	0.45	0.36	703-1064-03-S
	64	8 x 10	8 x 8	0.45	0.35	703-1064-04-S
	64	8 x 11	8 x 8	0.30	0.25	703-1064-05-S
	64	8 x 12	8 x 8	0.40	0.35	703-1064-06
	64	8.1 x 11.1	8 x 8	0.45	0.35	703-1064-07
64	8.1 x 8.1	8 x 8	0.45	0.35	703-1064-08	
64	8 x 13	8 x 8	0.40	0.35	703-1064-09	
64	8.1 x 12.1	8 x 8	0.45	0.35	703-1064-11	
72	8 x 11	8 x 12	0.45	0.35	703-1072-01	
80	8 x 14	8 x 10	0.45	0.35	703-1080-01	
84	8 x 11	8 x 12	0.45	0.35	703-1084-01	
88	8 x 11	8 x 12	0.45	0.35	703-1088-01	
96	8 x 11	8 x 12	0.45	0.35	703-1096-01	

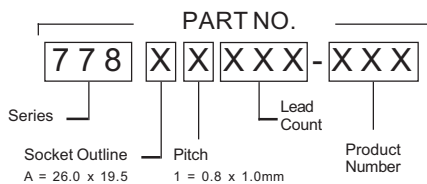
778 Series OTCSP Pinch Socket

- Open Top Chip Scale Package
- Accommodates pitch size of 0.80mm x 1.00mm
- Compact size and Low Actuation Force
- 4-Point pinch design for enhanced electrical contact
- Unique mechanism to eliminate solder ball sticking
- Maximum package size is 11.0 x 18.5mm



Pitch e (mm)	Ball Count	Package Size	Matrix Contact	Ball Dia. (mm)	Ball Height (mm)	Contact Plating	Part Number	Socket Outline (mm)
0.80 X 1.0	55	11 X 18.5	12 X 18	0.35	0.24	Au	778A1055-101	19.5 x 26
	55	11 X 18.5	12 X 18	0.51	0.39	Au	778A1055-102	19.5 x 26
	144	11 X 18.5	12 X 18	0.35	0.24	Au	778A1144-101	19.5 x 26
	144	11 X 18.5	12 X 18	0.51	0.39	Au	778A1144-102	19.5 x 26

DESCRIPTION & ORDERING INFORMATION

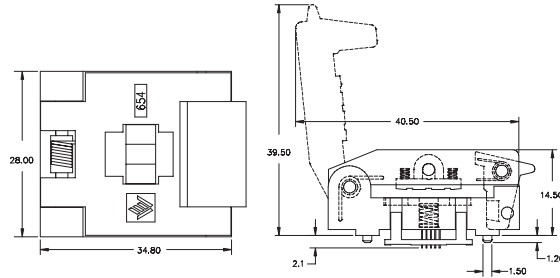


MATERIALS & SPECIFICATIONS

- Socket Body: PES, PEI, LCP or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: Gold or NiPd
- Contact Normal Force: 10 grams per pin
- Contact Current Rating: 0.5 amps
- Contact Resistance: 100 mΩ max
- Dielectric: 700V AC for 1 min.
- Insulation Resistance: 1,000 MΩ @ 500V DC
- Temperature Rating: 150°C
- Durability: 10,000 cycles

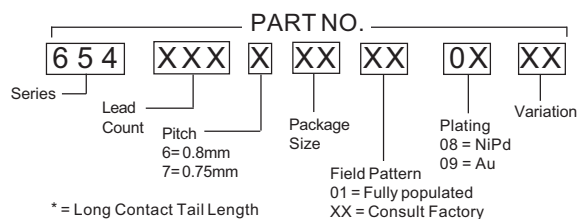
654 Series FBGA/CSP Socket

- Clamshell design with patented “Y” contact
- Two points of contact with lead scrub
- Pivoting pressure pad for uniform pressure
- Modular design allows for easy customization
- Spring loaded ejection



Pitch e (mm)	Lead Count	Package Size (mm)	Matrix	Ball Dia.(mm)	Ball Height (mm)	Part Number
0.75	40	7.71 X 10.15	5 X 8	0.30	0.30	654040728010811
	48	7.27 X 8.87	6 X 8	0.33	0.25 min.	654048728010816
	48	7.1 X 7.18	6 X 8	0.35	0.24 min.	654048728010823
	48	7 X 8	6 X 8	0.30	0.30	654048728010824
0.80	48	6 X 8	6 X 8	0.40	0.35	654048628010806
	48	5.95 X 8.95	6 X 8	0.40	0.35	654048631010806
	48	5.95 X 9.95	6 X 8	0.40	0.35	654048633010806
	48	7.95 X 8.95	6 X 8	0.40	0.35	654048632010806
	48	6 X 12	6 X 8	0.45	0.30	654048628010818
	48	8 X 11	6 X 8	0.45	0.30	654048629010818
	48	7 X 12	6 X 8	0.30	0.30	654048628010822
	56	9 X 13	4 X 14	0.50	0.40	654056628020940
	60	8 X 16	4 X 15	0.40	0.25 min.	654060628020822
	60	9.55 X 17.32	4 X 15	0.50	0.35	654060628020815
	60	8 X 16	4 X 15	0.40	0.25 min.	654060629020822
	64	8 X 8	8 X 8	0.50	0.40	654064608010813
	64	8 X 8	8 X 8	0.50	0.40	654064608010817
	72	8 X 8	9 X 9	0.50	0.40	654072608020837
	72	11 X 11	8 X 12	0.45	0.35	654072611020814
	73	9 X 9	9 X 9	0.50	0.35	654073609020809
	80	8 X 8	9 X 9	0.50	0.40	654080608020813
	81	8.1 X 8.1	9 X 9	0.45	0.35	654081608010814
	81	9 X 9	9 X 9	0.48	0.35	654081609010833
	104	13 X 13	13 X 13	0.50	0.30	654104613020925
	109	11 X 11	12 X 12	0.50	0.30	654109611020809
	112	10 X 10	11 X 11	0.50	0.40	654112610020817*
	112	10 X 10	11 X 11	0.50	0.40	654112610020821
	113	10 X 10	11 X 11	0.50	0.35	654113610020809
	120	9 X 13	9 X 14	0.50	0.40	654120628020807
	121	10 X 10	11 X 11	0.45	0.35	654121610010824
	126	9 X 13	9 X 14	0.50	0.40	654126628010931
	128	11 X 11	12 X 12	0.50	0.40	654128612020817
	144	12 X 12	13 X 13	0.50	0.40	654144612020807
	144	12 X 12	13 X 13	0.50	0.40	654144612020907
	144	12 X 12	13 X 13	0.50	0.40	654144612020817*
	168	12 X 12	14 X 14	0.50	0.40	654168612020913
169	12 X 12	13 X 13	0.50	0.40	654169612010907	

DESCRIPTION & ORDERING INFORMATION

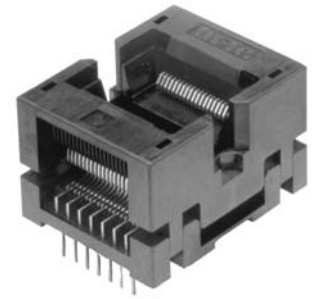


MATERIALS & SPECIFICATIONS

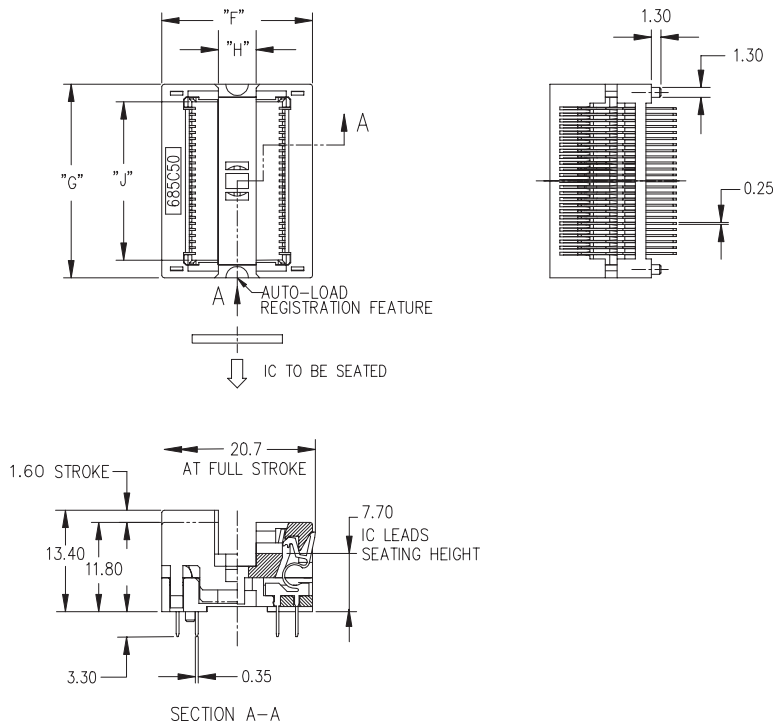
- Socket Body: LCP, PES, PEI or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: NiPd or Gold
- Contact Normal Force: 13 grams
- Contact Resistance: 100 mΩ max.
- Dielectric: 500V AC for 1 minute
- Temperature Rating: 150°C
- Insulation Resistance: 1000 MΩ @ 500V DC
- Durability: 10,000 cycles min.

685 Series SON CSP Socket

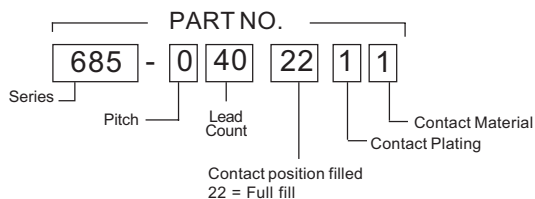
- For Small Outline No lead packages
- Open top, Zero Insertion Force design for automatic loading
- Highly reliable contact design with wiping action
- Designed for 0.50mm pitch packages



Part Number: 685-0402211



DESCRIPTION & ORDERING INFORMATION

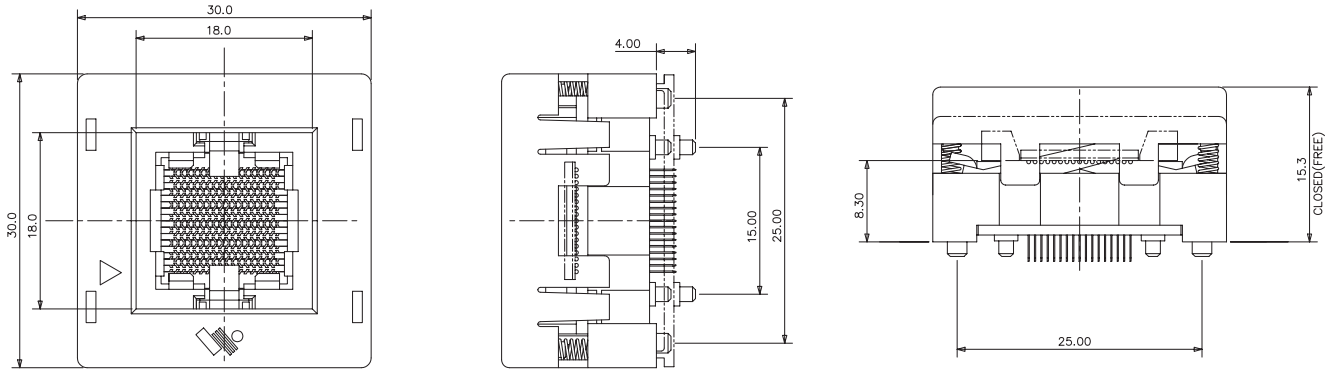
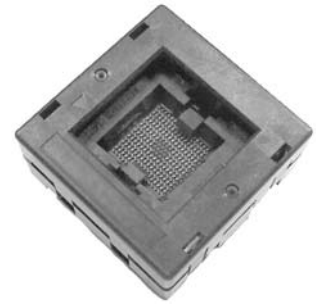


MATERIALS & SPECIFICATIONS

- Socket Body: PEI, PES, LCP or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: Gold over Nickel
- Contact Normal Force: 35 grams
- Contact Resistance: 50 mΩ
- Dielectric: 600V AC for 1 minute
- Temperature Rating: 150°C
- Insulation Resistance: 5,000 MΩ @ 500V DC
- Durability: 10,000 cycles min.

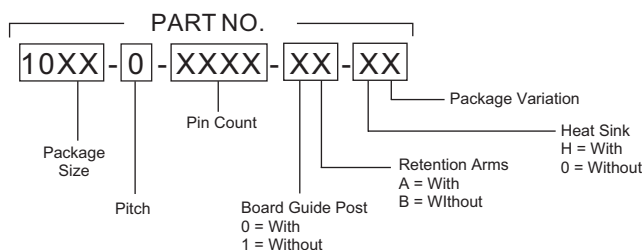
1000-0 Series 0.65mm Pitch CSP

- Open top, vertically actuated
- Pinch and scrub contact system
- Dual moving beams per contact
- Two points of contact per solder ball
- Board mounting features
- Through hole contact
- Maintains package position for ease of handler programming



Pitch e (mm)	Lead Count	Package Size	Matrix	Ball Dia. (mm)	Part Number	Socket Dimensions (mm)		
						Length (A)	Width (B)	Height (C)
0.65	241	11X11	16X16	0.4 +/- 0.05	1011-0-0241-0A-00	30.0	30.0	15.3
	169	9X9	13X13	0.4 +/- 0.05	1009-0-0169-0B-00	38.0	38.0	15.8
	204	13X13	20X20	0.3 +/- 0.05	1013-0-0204-0B-00	38.0	38.0	15.8
	204	12X12	18X18	0.4 +/- 0.05	1012-0-0204-0A-00	38.0	38.0	15.8
	204	12X12	18X18	0.4 +/- 0.05	1012-0-0204-0B-00	38.0	38.0	15.8
	237	13X13	19X19	0.4 +/- 0.05	1013-0-0237-0A-00	38.0	38.0	15.8
	256	11X11	16X16	0.4 +/- 0.05	1011-0-0256-0B-00	38.0	38.0	15.8
	256	12X12	16X16	0.4 +/- 0.05	1012-0-0256-0A-00	38.0	38.0	15.8
	280	13X13	19X19	0.3 +/- 0.05	1013-0-0280-0B-00	38.0	38.0	15.8
	336	13X13	19X19	0.3 +/- 0.05	1013-0-0336-0A-00	38.0	38.0	15.8
	348	13X13	19X19	0.3 +/- 0.05	1013-0-0348-0A-00	38.0	38.0	15.8
	364	14X14	20X20	0.4 +/- 0.05	1014-0-0364-0A-00	38.0	38.0	15.8
	372	15X15	22X22	0.3 +/- 0.05	1015-0-0372-0B-00	38.0	38.0	15.8
	372	15X15	22X22	0.3 +/- 0.05	1015-0-0372-0A-00	38.0	38.0	15.8
380	16X16	24X24	0.4 +/- 0.05	1016-0-0380-0B-00	38.0	38.0	15.8	
380	16X16	24X24	0.4 +/- 0.05	1016-0-0380-0A-00	38.0	38.0	15.8	

DESCRIPTION & ORDERING INFORMATION



*Available contact tail length: 2.0mm length only

MATERIALS & SPECIFICATIONS

- Socket Body and Lid: PES
- Contact: BeCu, Gold over Nickel Plated
- Metal Components: Stainless Steel
- Contact Force: 8.5 grams
- Actuation Force: 5 Kg for full grid
- Contact Resistance: < 50 mΩ
- Dielectric Withstanding Voltage: 100V RMS
- Current Carrying Capability: 0.5A
- Insulation Resistance: > 1000 mΩ at 100V DC
- Temperature Rating: -55°C to +150°C
- Durability: 10,000 cycles (1 cycle - 1 load and 1 unload)